

IGBT Chip in NPT-technology

**FEATURES:**

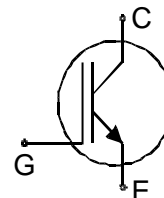
- 600V NPT technology
- 100µm chip
- short circuit prove
- positive temperature coefficient
- easy paralleling

**This chip is used for:**

- SGP10N60

**Applications:**

- drives



Chip Type	V <sub>CE</sub>	I <sub>Cn</sub>	Die Size	Package	Ordering Code
SIGC12T60SNC	600V	10A	3.5 x 3.5 mm <sup>2</sup>	sawn on foil	Q67041-A4664-A001
SIGC12T60SNC	600V	10A	3.5 x 3.5 mm <sup>2</sup>	unsawn	Q67041-A4664-A002

**MECHANICAL PARAMETER:**

Raster size	3.5 x 3.5	mm <sup>2</sup>
Area total / active	12.25 / 8.7	
Emitter pad size	1.99 x 1.58	
Gate pad size	1.1 x 0.694	
Thickness	100	µm
Wafer size	150	mm
Flat position	270	deg
Max.possible chips per wafer	1219	
Passivation frontside	Photoimide	
Emitter metallization	3200 nm Al Si 1%	
Collector metallization	1400 nm Ni Ag –system suitable for epoxy and soft solder die bonding	
Die bond	electrically conductive glue or solder	
Wire bond	Al, ≤500µm	
Reject Ink Dot Size	Ø 0.65mm ; max 1.2mm	
Recommended Storage Environment	store in original container, in dry nitrogen, < 6 month at an ambient temperature of 23°C	

## MAXIMUM RATINGS:

Parameter	Symbol	Value	Unit
Collector-emitter voltage, $T_j=25\text{ °C}$	$V_{CE}$	600	V
DC collector current, limited by $T_{jmax}$	$I_C$	1)	A
Pulsed collector current, $t_p$ limited by $T_{jmax}$	$I_{Cpuls}$	30	A
Gate emitter voltage	$V_{GE}$	$\pm 20$	V
Operating junction and storage temperature	$T_j, T_{stg}$	-55 ... +150	$^{\circ}\text{C}$

1) depending on thermal properties of assembly

## STATIC CHARACTERISTICS (tested on chip), $T_j=25\text{ °C}$ , unless otherwise specified:

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
Collector-emitter breakdown voltage	$V_{(BR)CES}$	$V_{GE}=0V, I_C=500\mu A$	600			V
Collector-emitter saturation voltage	$V_{CE(sat)}$	$V_{GE}=15V, I_C=10A$	1.6	2	2.5	
Gate-emitter threshold voltage	$V_{GE(th)}$	$I_C=300\mu A, V_{GE}=V_{CE}$	3	4	5	
Zero gate voltage collector current	$I_{CES}$	$V_{CE}=600V, V_{GE}=0V$			0.85	$\mu A$
Gate-emitter leakage current	$I_{GES}$	$V_{CE}=0V, V_{GE}=20V$			100	nA

## DYNAMIC CHARACTERISTICS (tested at component):

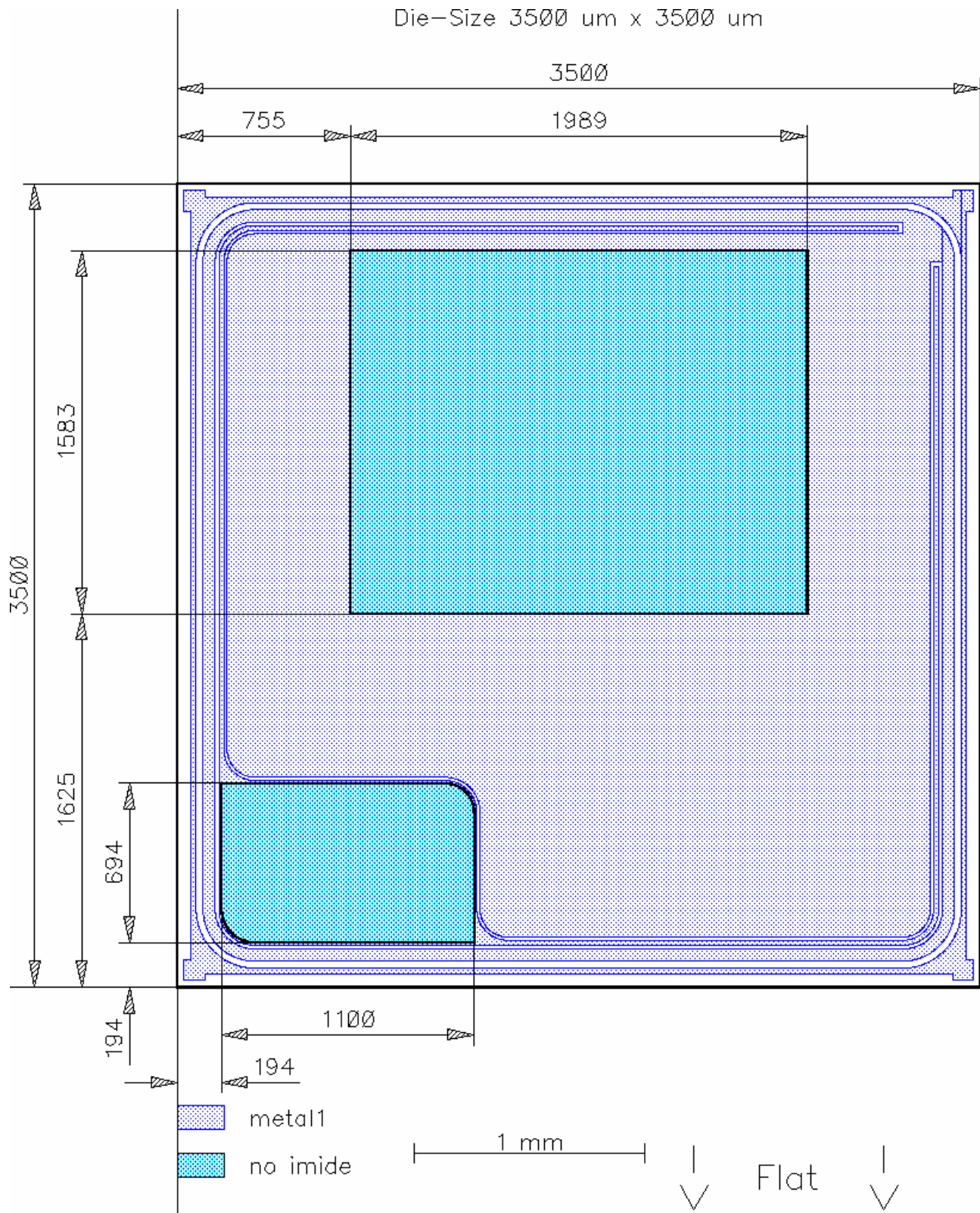
Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
Input capacitance	$C_{iss}$	$V_{CE}=25V$	-	580	696	pF
Output capacitance	$C_{oss}$	$V_{GE}=0V$	-	70	84	
Reverse transfer capacitance	$C_{riss}$	$f=1MHz$	-	50	60	

## SWITCHING CHARACTERISTICS (tested at component), Inductive Load:

Parameter	Symbol	Conditions <sup>2)</sup>	Value			Unit
			min.	typ.	max.	
Turn-on delay time	$t_{d(on)}$	$T_j=150\text{ °C}$	-	29	35	ns
Rise time	$t_r$	$V_{CC}=400V$	-	21	25	
Turn-off delay time	$t_{d(off)}$	$I_C=10A$	-	266	319	
Fall time	$t_f$	$V_{GE}=+15/0V$	-	63	76	
		$R_G=25\Omega$				

<sup>2)</sup> switching conditions different to 600V Standard IGBT 2, under comparable switching conditions 40% faster turnoff than Standard IGBT 2. Values also influenced by parasitic L- and C- in measurement and package.

**CHIP DRAWING:**





# SIGC12T60SNC

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**FURTHER ELECTRICAL CHARACTERISTICS:**

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This chip data sheet refers to the device data sheet

SGP10N60

Package :TO220

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**Description:**

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AQL 0,65 for visual inspection according to failure catalog

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Electrostatic Discharge Sensitive Device according to MIL-STD 883

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Test-Normen Villach/Prüffeld

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